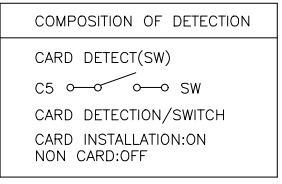
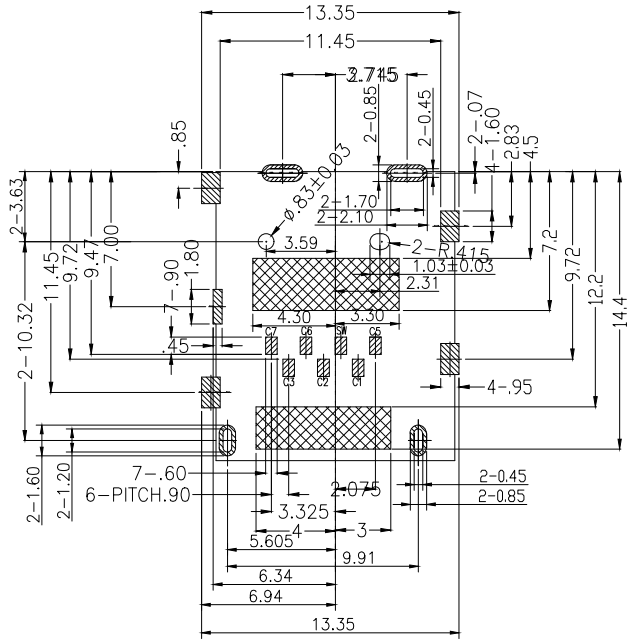
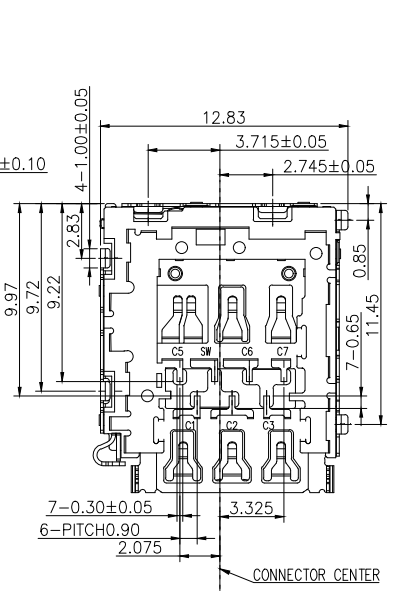
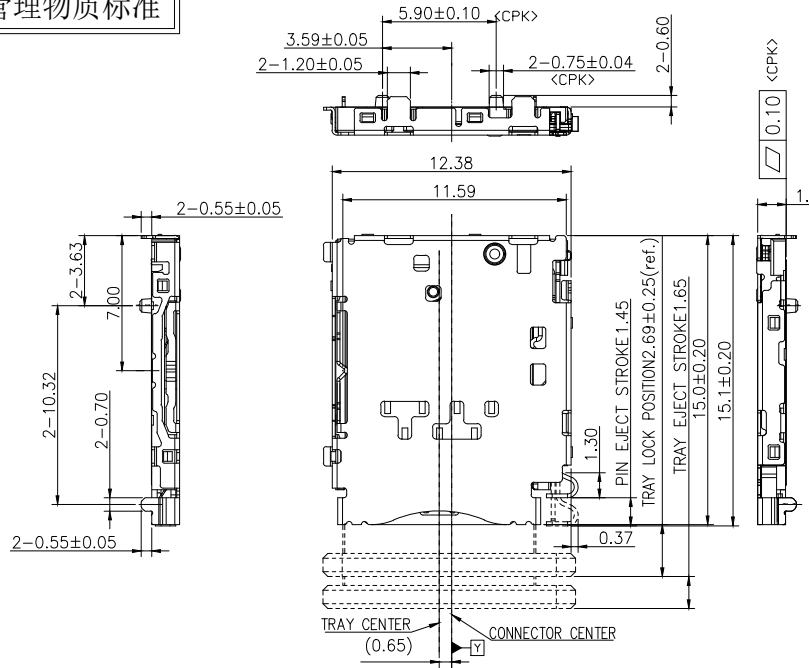
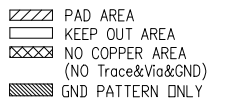


符合环境
管理物质标准

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2023/04/11



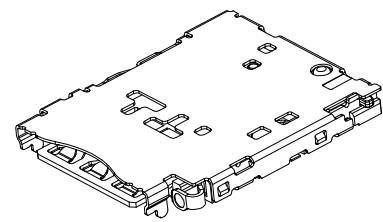
RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



- NOTE:
- Material:
 - Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
 - Cover: SUS304-H T=0.15±0.03mm
 - Plating:
 - Contact terminal:
 - Contact area: Gold 3u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
 - Specification:
 - Current Rating :0.5A max.
 - Contact Resistance: 50 mOhms max
 - Insulation Resistance: 1000 MOhms min./500VDC
 - Dielectric Withstanding Voltage: 500 V AC/1minute
 - Operating Temperature: -25°C to +85°C
 - Mating Cycles: 5000 Insertions
 - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 - Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



GENERAL TOLERANCE	DWG NO.	APPD:	Scale	1:1	
X.±0.45	x.'±5°	Title	NANO SIM PUSH PULL H1.5 CARD CONNDIP)	UNIT	mm
.X±0.35	.x'±2°	DR:	TEDDY		
.XX±0.25	.xx'±1°	Part NO.	C-S40715024-2		Date
.XXX±0.15	.xxx'±0.5°	东莞市铭标电子科技有限公司 Ming Biao Electronic Technology Co., Ltd.			
SHEET	1/2				